Final Product Change Notification | 201810024F01

Issue Date: 19-Nov-2018
Effective Date: 17-Feb-2019

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Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[ ] Other			

Substrate Metal Trace Spacing Change at Package Edge for Kinetis K22-120 MHz and K21-120 MHz Devices Assembly in UDG

Description of Change

NXP Semiconductors announces the enlargement of the metal trace from 45 um to 84 um at package edge of Kinetis K22-120 MHz and K21-120 MHz devices assembly in UTAC, Dongguan, China (UDG).

The metal trace enlargement was successfully qualified adhering to NXP specifications.

Please see the attached file(s) for additional details.

Reason for Change

Align the metal trace spacing at package edge with NXP latest guideline. The enlarged spacing has better performance than old spacing.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information
Samples are available from 06-Nov-2018
The following sample part number is available:
PK21FN1M0AVMC12
For samples with other part numbers, NXP will deliver within 6 weeks after we receive the request.
Production
Planned first shipment 06-Feb-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 19-Dec-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Affected Part Numbers

MK22FN1M0AVMC12
MK22FX512AVMC12